MA3X727 (MA727)

Silicon epitaxial planar type

For super high speed switching For small current rectification

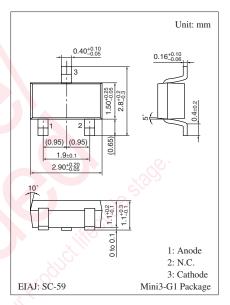
■ Features

- Reverse voltage $V_R = 50 \text{ V}$ is guaranteed
- Forward current (Average) $I_{F(AV)} = 200$ mA rectification is possible

■ Absolute Maximum Ratings $T_a = 25$ °C

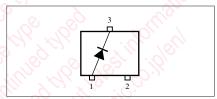
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	50	V
Repetitive peak reverse voltage	V _{RRM}	50	V
Peak forward current	I_{FM}	300	mA
Forward current (Average)	$I_{F(AV)}$	200	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	Tj	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M1Z

Internal Connection

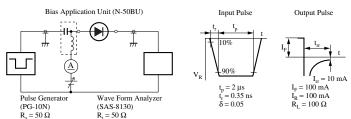


■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 30 \text{ mA}$	150		0.36	V
	V_{F2}	I _F = 200 mA			0.55	V
Reverse current	I_R	$V_R = 50 \text{ V}$			200	μΑ
Terminal capacitance	C _t	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		30		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		3.0		ns
Wall.		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

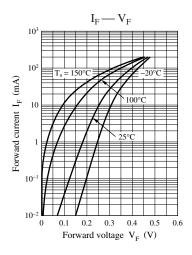
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 1 GHz.

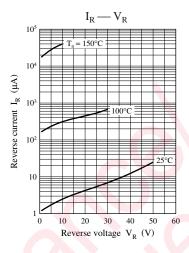


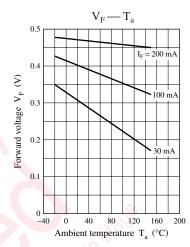


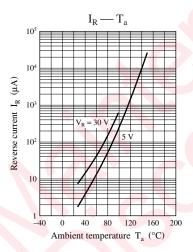
Note) The part number in the parenthesis shows conventional part number.

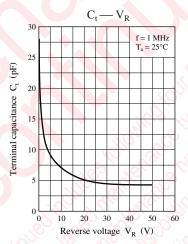
Panasonic











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